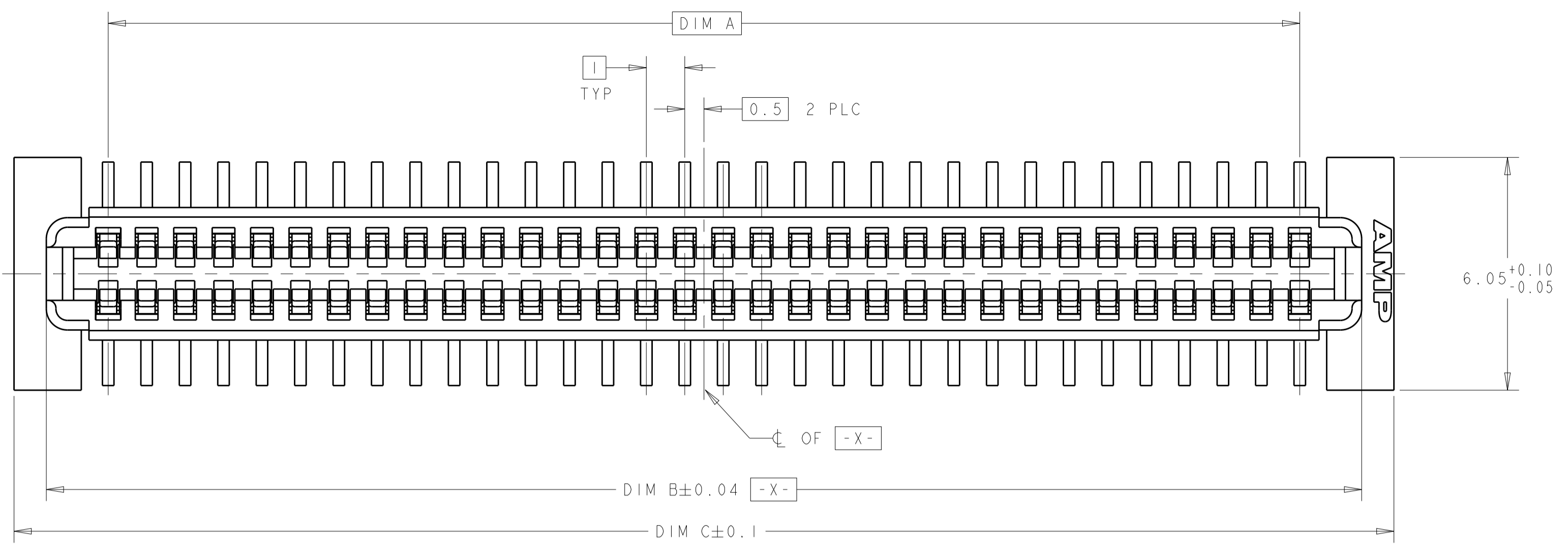
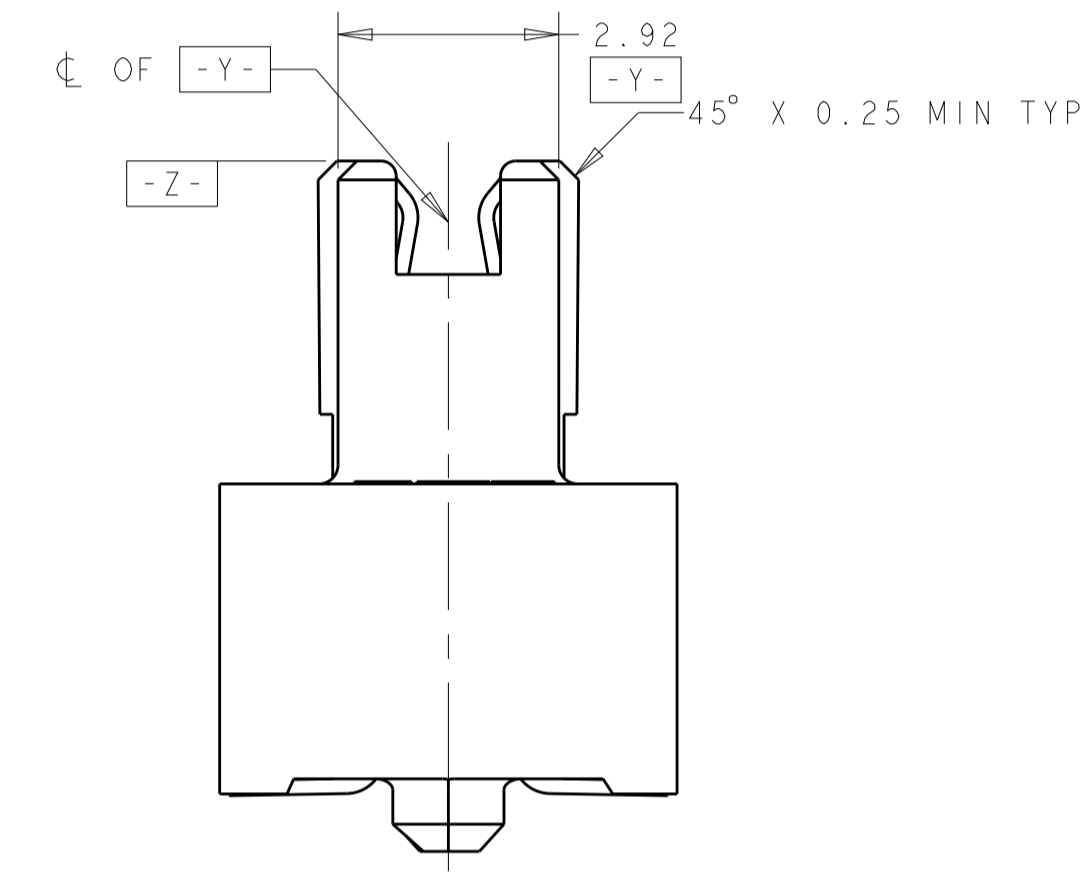
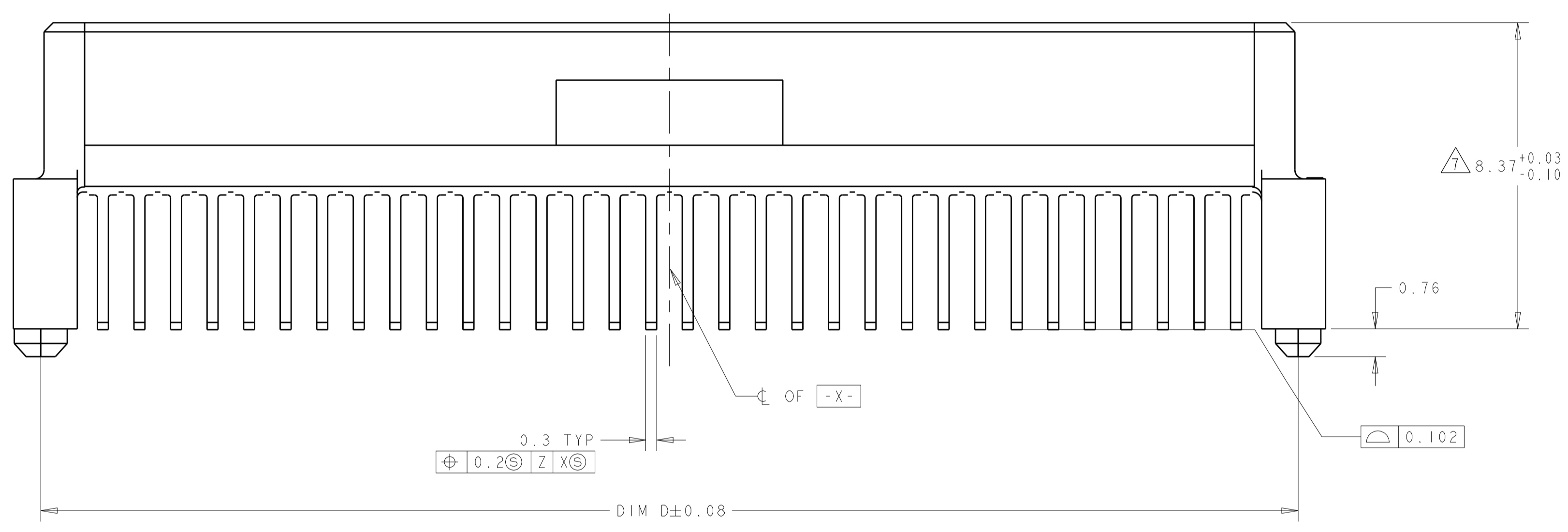


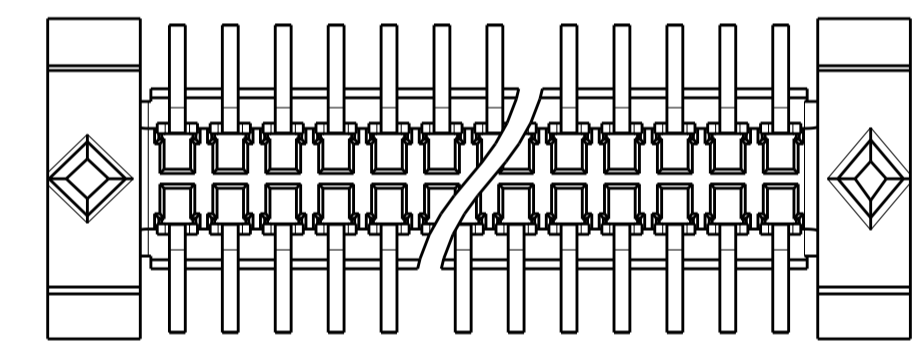
REVISIONS				
P.	LTN.	DESCRIPTION	DATE	APPV.
J		REVISED PER ECR-14-016951	11FEB2015	L.T. W.H.



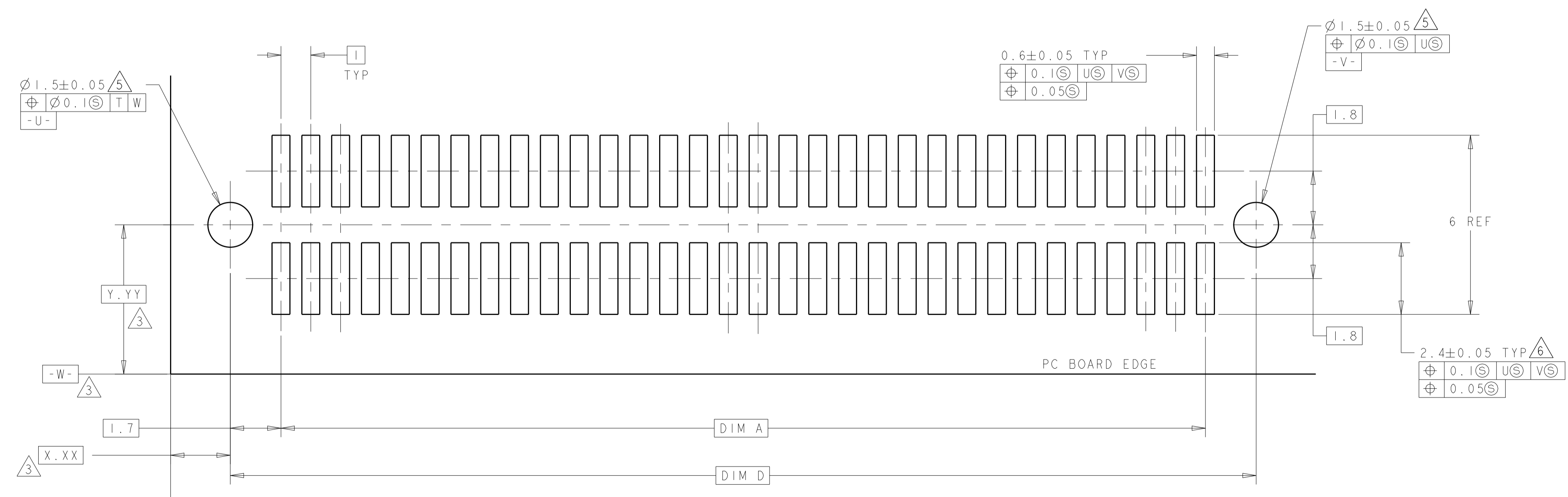
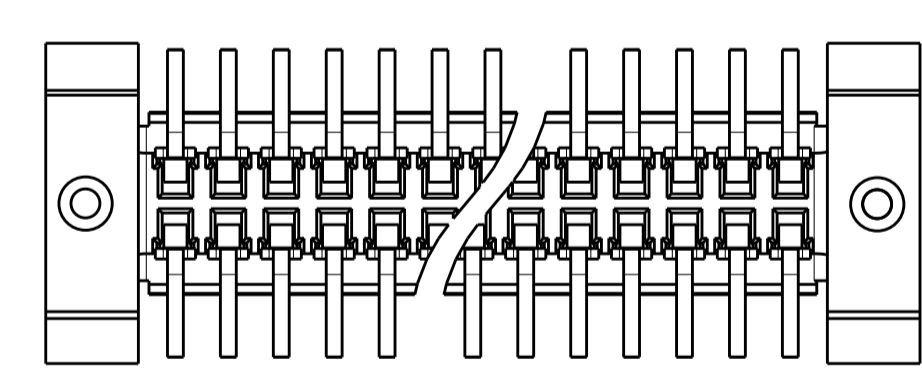
1. HOUSING MATERIAL: HIGH TEMPERATURE THERMOPLASTIC, COLOR; BLACK. CONTACT MATERIAL: PHOSPHOR BRONZE.
2. CONTACT FINISH: NICKEL UNDERPLATE ALL OVER, MATING SURFACES PLATED TO MEET PLI PERFORMANCE REQUIREMENTS OF INDUSTRY SPECIFICATION EIA-700AAAB, SOLDER TAILS PLATED TIN-LEAD.
3. DATUM LOCATIONS AND BASIC DIMENSIONS TO BE ESTABLISHED BY THE CUSTOMER. CONSULT AMP ENGINEERING WHEN PLACING MULTIPLE CONNECTORS ON A PC BOARD.
4. PACKAGED IN TAPE ON REEL PER EIA-481.
5. 1.5 MIN DIAMETER HOLE SHOULD BE USED IF USING POST STYLE "A" AND PLACING ON PCB WITH VACUUM PLACEMENT EQUIPMENT.
6. SHORTER SOLDER LANDS MAY BE USED PER EIA 700AAAB, HOWEVER 2.4 LENGTH ASSURES OPTIMUM SOLDER FILLET REGARDLESS OF MANUFACTURER OF CONNECTOR.
7. REFERRED TO AS DIM H = 8.3±0.1 IN EIA 700AAAB SPECIFICATION.
8. CONTACT FINISH: 0.002 MINIMUM BRIGHT TIN-LEAD (93-7) ON SOLDER AREA, 0.00127 MINIMUM GOLD ON MATING AREA, BOTH OVER 0.00127 MINIMUM NICKEL ON ENTIRE CONTACT.
9. SQUARE AND DIAMOND SHAPED POSTS
10. ROUND SHAPED POSTS



9 STYLE A POST



10 STYLE B POST



RECOMMENDED PC BOARD LAYOUT

POST STYLE	FINISH	DIM D	DIM C	DIM B	DIM A	STACK HGTS	POS	PART NO
8	8	44.4	45.9	44.22	41	13	84	3-120523-2
8	8	34.4	35.9	34.22	31	13	64	3-120523-1
2	2	44.4	45.9	44.22	41	13	84	2-120523-2
2	2	34.4	35.9	34.22	31	13	64	2-120523-1
8	8	44.4	45.9	44.22	41	13	84	1-120523-2
8	8	34.4	35.9	34.22	31	13	64	1-120523-1
2	2	44.4	45.9	44.22	41	13	84	120523-2
2	2	34.4	35.9	34.22	31	13	64	120523-1

THIS DRAWING IS A CONTROLLED DOCUMENT.

AWN: J. REED 27/11/97
CHK: L. VO 27/11/97

TE Connectivity

RCPT ASSY, 1.0mm FH(IEEE1386) CONNECTOR

PRODUCT SPEC: 502-1079
APPLICATION SPEC: 114-25045

SCALE: 10:1 SHEET: 1 OF 1 REV: J